



## MOSFETs Silicon 430V N-Channel MOS

**■ Applications**

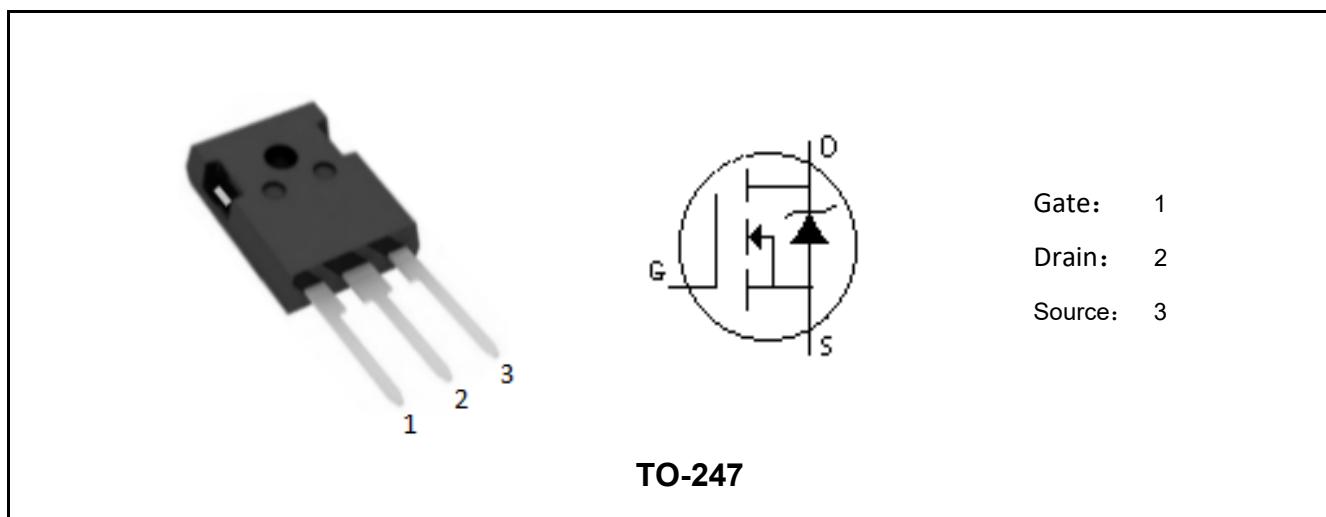
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

**■ Features**

- Low  $R_{DS(ON)}$
- Ultra Low Gate Charge
- RoHS Compliant
- 100% UIS and RG Tested

**■ Product Summary**

$V_{DS}$	430	V
$I_D$	11	A
$R_{DS(ON),Typ}@10V$	0.47	$\Omega$
$Q_g$	20	nC



Marking	Package	Packaging	Min. package quantity
MSIRF11N45	TO-247	Tube	450





## ■ Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	430	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current T <sub>c</sub> =25°C (Note 1)	I <sub>D</sub>	11	A
Continuous Drain Current T <sub>c</sub> =100°C (Note 1)		6.8	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	44	A
Total Dissipation	P <sub>D</sub>	96	W
Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55-150	°C
Single Pulse Avalanche Energy (Note 2)	E <sub>AS</sub>	450	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

## ■ Thermal Characteristics

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	R <sub>θJC</sub>	1.3	°C/W
Maximum Junction-to-Ambient	R <sub>θJA</sub>	60	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V<sub>DD</sub>=50V, T<sub>ch</sub>= 25°C(initial), I<sub>AS</sub>=11A, R<sub>g</sub>=25Ω.

Note 3: The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25° C. The value in any given application depends on the user's specific board design.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





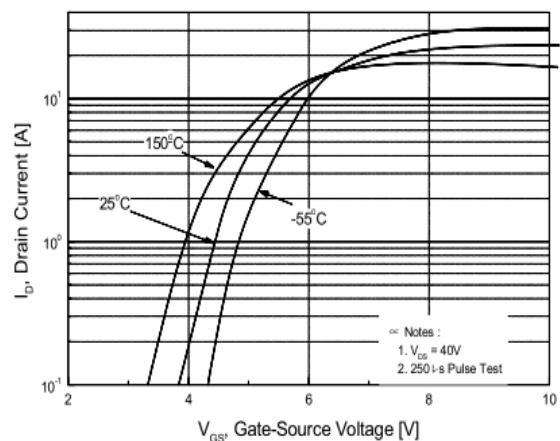
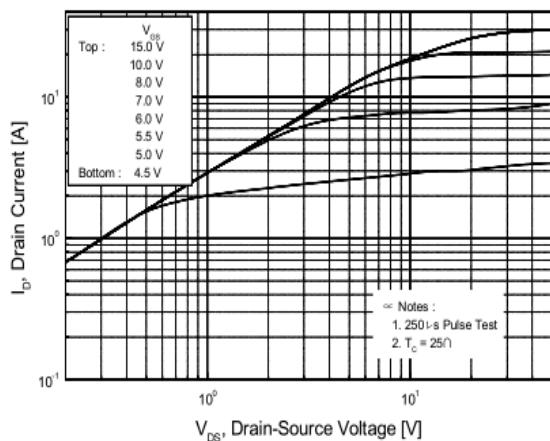
■ Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	B <sub>V<sub>DSS</sub></sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	430	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =430V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	3	4	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.5A	-	0.47	0.5	Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	1120	-	pF
Output Capacitance	C <sub>oss</sub>		-	118	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	10	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	2	-	Ω
<b>Switching Paramters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =250V, I <sub>D</sub> =11A, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω	-	32	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	28	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	90	-	ns
Turn-Off Rise Time	t <sub>f</sub>		-	50	-	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =320V, I <sub>D</sub> =11A, V <sub>GS</sub> =10V	-	20	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	6.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	4.5	-	nC
<b>Source-Drain Characteristics</b>						
Max. Diode Forward Cuurent	I <sub>S</sub>		-	-	11	A
Max. Pulsed Forward Cuurent	I <sub>SM</sub>		-	-	44	A
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =11A	-	0.86	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =320V, I <sub>F</sub> =11A, di/dt=100A/us	-	320	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	3.2	-	μC

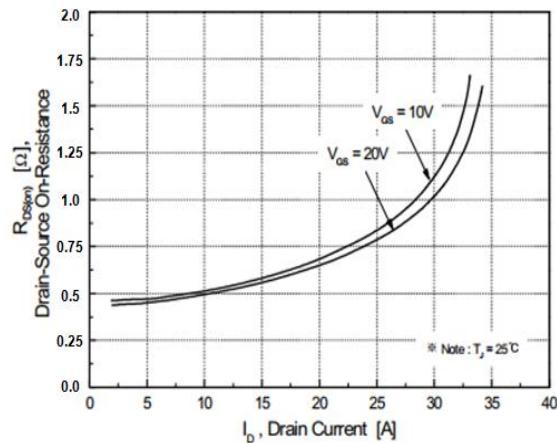




## ■ Characteristics Curves

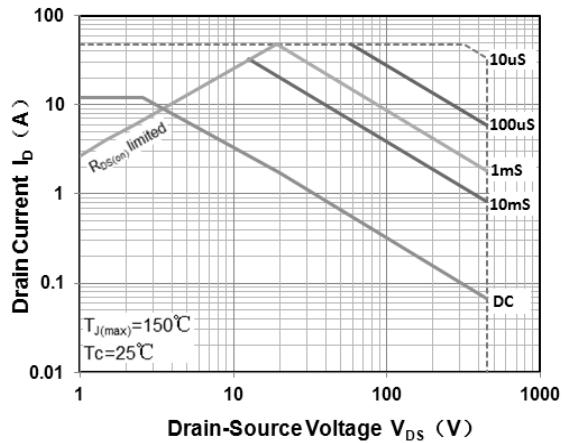


Output Characteristics

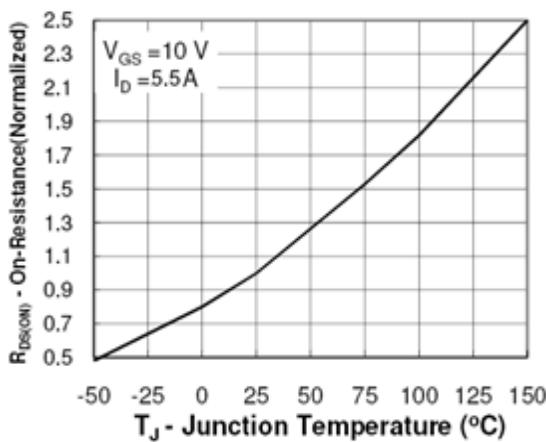


On Resistance Vs Drain Current

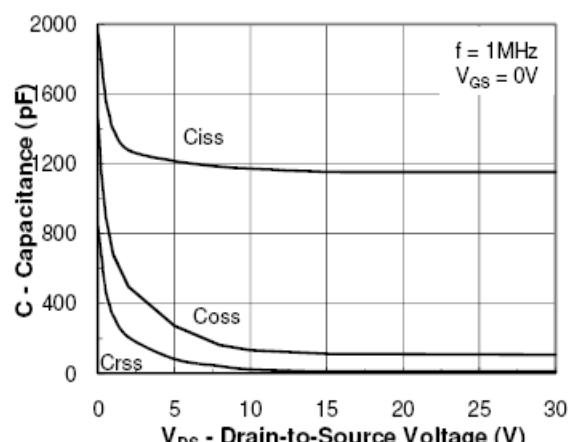
Transfer Characteristics



Safe Operating Area



Rdson-JunctionTemperature



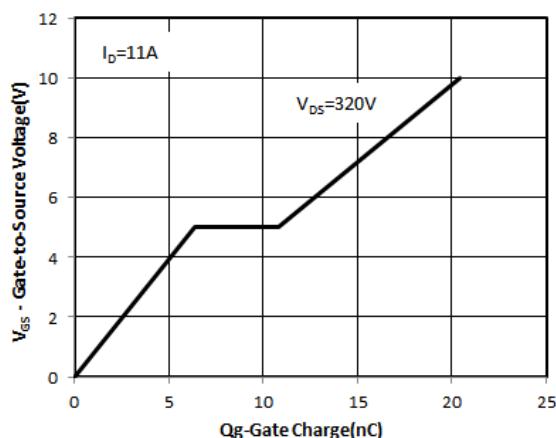
Capacitance



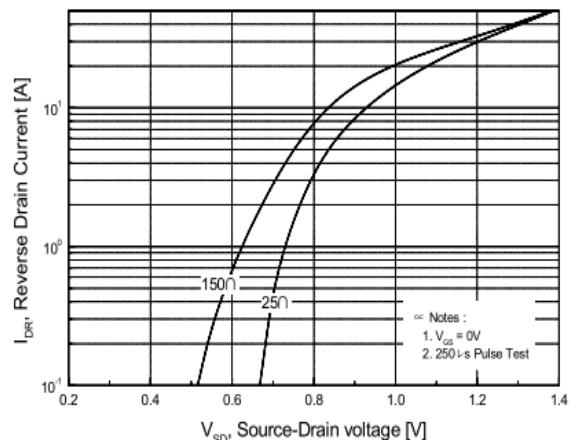


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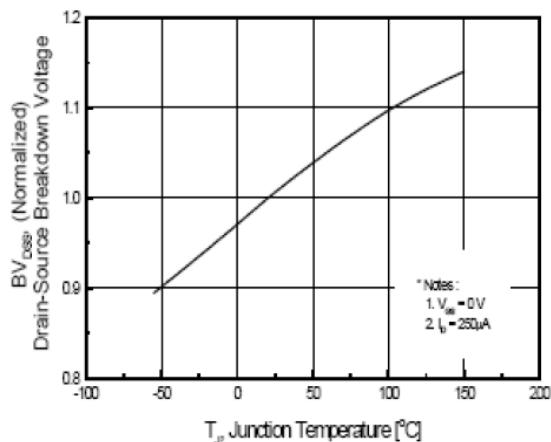
MSIRF11N45



Gate Charge Waveform



Source-Drain Diode Forward Voltage



Breakdown Voltage Vs Junction Temperature

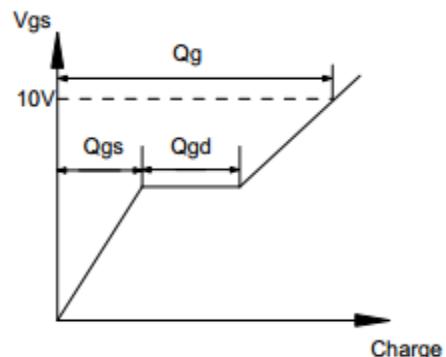
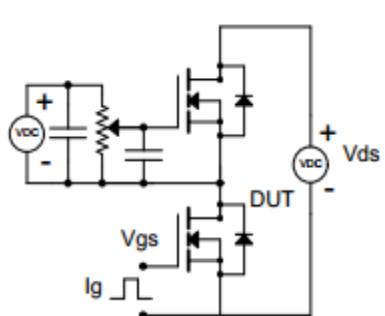
Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



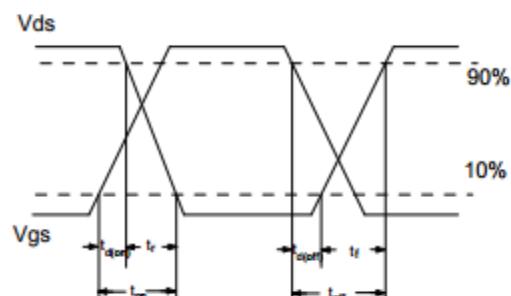
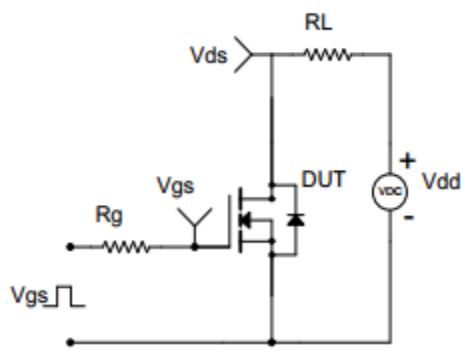


## ■ Test Circuit & Waveform

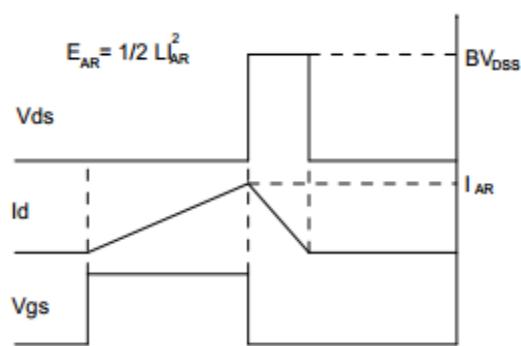
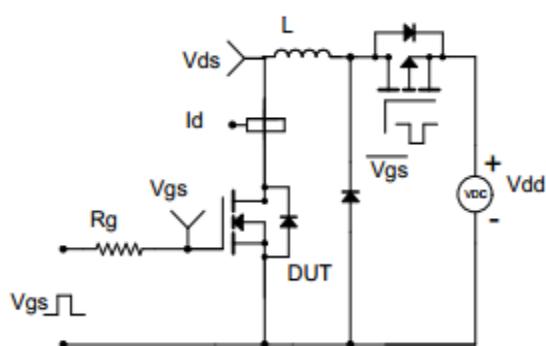
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveform





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MSIRF11N45

**■ TO-247 Package Dimensions**

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	4.60		5.15	A1	1.30		1.60
b	2.86		3.26	b1	1.86		2.26
b2		1.20		C		0.50	
D	19.00		21.00	E	15.45		15.75
E1	12.00		13.06	e		5.45	
L	14.00		14.60	L1	5.20		5.88
L2	24.00		24.40	L3	10.00		10.60
ΦP		3.50		Q	2.30		2.70

